

SSCE3V382N1

Ultra-low Capacitance Bidirectional Micro Packaged TVS Diodes for ESD Protection

Description

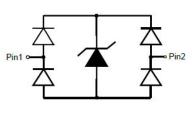
The SSCE3V382N1 is designed with SSC Punch-Through process TVS technology to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as USB 2.0 high speed, USB 3.0 super speed, VGA, DVI, HDMI,SDI and other high speed line applications.

It has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by ESD(electrostatic discharge), and EFT (electrical fast transients).

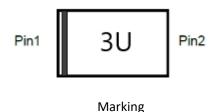
Feature

- \Rightarrow 32W peak pulse power (tP = 8/20µs)
- ♦ DFN1006-2L Package
- ♦ Working voltage: 3.3V
- ♦ Low clamping voltage
- ♦ Low capacitance(0.40pF) for high-speed interfaces
- ♦ Low clamping voltage: VCL = 9.0V typ. @ IPP = 16A (TLP)
- ♦ RoHS compliant
- ♦ Complies with following standards:
 - -IEC61000-4-2(ESD) $\pm 15KV(contact), \pm 20KV(air)$
 - -IEC61000-4-5 (Lightning) 3.5A (8/20 μ s)

PIN configuration



DFN1006-2L



Applications

- ♦ High Speed Line: USB1.0/2.0/3.0/3.1, VGA, DVI, SDI
- High Definition Multi-Media Interface (HDMI1.3/1.4/2.0)
- ♦ Serial and Parallel Ports
- ♦ Notebooks, Desktops, Servers
- ♦ Cellular handsets and accessories
- ♦ Portable instrumentation
- ♦ Peripherals

• Mechanical data

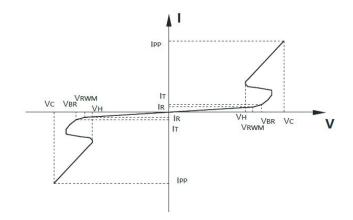
- ♦ Lead finish:100% matte Sn(Tin)
- ♦ Mounting position: Any
- \diamond Qualified max reflow temperature:260°C
- ♦ Device meets MSL 1 requirements
- \Rightarrow Pure tin plating: $7 \sim 17$ um
- ♦ Pin flatness:≤3mil

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• Electronic Parameter

Symbol	Parameter		
V_{RWM}	Peak Reverse Working Voltage		
I_R	Reverse Leakage Current @ V _{RWM}		
V _{BR}	Breakdown Voltage @ I _T		
I _T	Test Current		
I _{PP}	Maximum Reverse Peak Pulse Current		
V _C	Clamping Voltage @ IPP		
P _{PP}	Peak Pulse Power		
С	Junction Capacitance		



Absolute maximum rating @TA=25°C

Symbol		Parameter	Value	Units
P _{PP}		Peak Pulse Power (8/20μS)	32	W
ESD Rating per IEC61000-4-2:	Contact	Vec	15	KV
	Air	VESD	20	
T _{STG}		Storage Temperature	-55/+150	$^{\circ}$ C
T _J		Operating Temperature	-55/+150	$^{\circ}$ C
TL		Lead Solder Temperature - Maximum	260	$^{\circ}$ C
		(10 Second Duration)	260	

• Electrical Characteristics @TA=25°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				3.3	V
Breakdown Voltage	V_{BR}	It = 1 mA	7.0	10.5		V
Reverse Leakage Current	I_R	VRWM =3.3V,		1	50	nA
Clamping Voltage ³⁾	$ m V_{CL}$	IPP = 1A, $tP = 8/20 \mu s$		3.6	5.5	V
		IPP=3.5A, $tP = 8/20\mu s$		5.2	7	V
Clamping Voltage ¹⁾	V_{CL}	IPP=16A, tP = 100ns		9		V
Dynamic resistance ¹⁾	Rdyn			0.3		Ω
Clamping Voltage ²⁾	V_{CL}	V _{ESD} =8KV		9		V
Junction Capacitance	CJ	VR=0V, f = 1MHz		0.35	0.50	pF

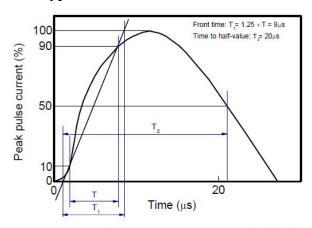
Notes:

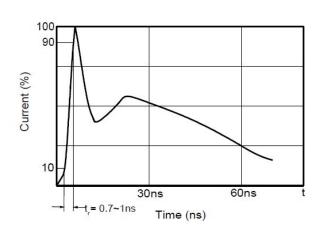
- 1) TLP parameter: $Z0 = 50 \Omega$, tp = 100ns, tr = 2ns, averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.

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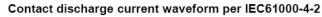


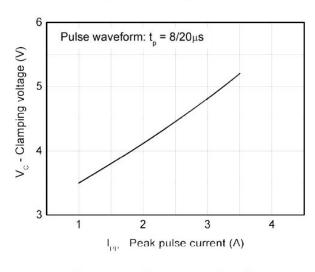
• Typical Performance Characteristics

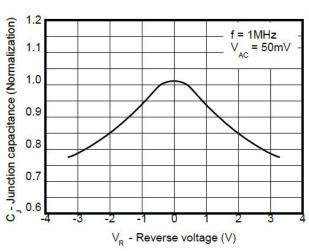




8/20µs waveform per IEC61000-4-5

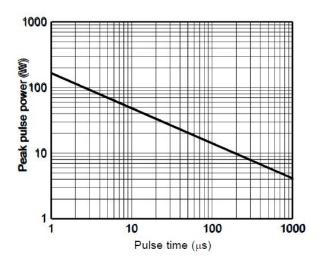


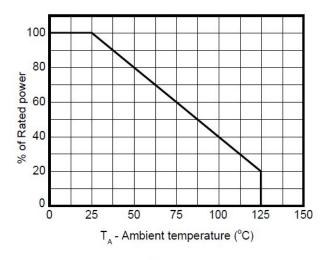




Clamping voltage vs. Peak pulse current

Capacitance vs. Reverse voltage





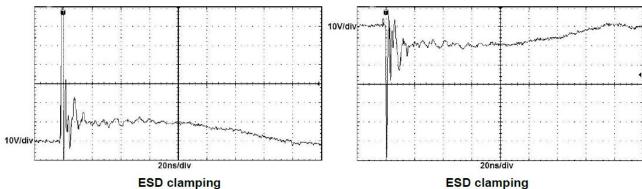
Non-repetitive peak pulse power vs. Pulse time

Power derating vs. Ambient temperature

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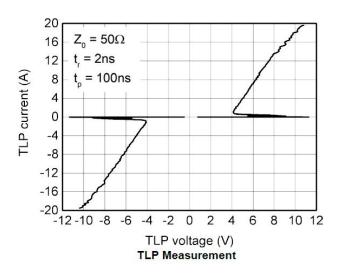


• Typical Performance Characteristics



(+8kV contact discharge per IEC61000-4-2)

(-8kV contact discharge per IEC61000-4-2)





• Package Information

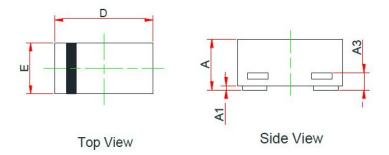
Ordering Information

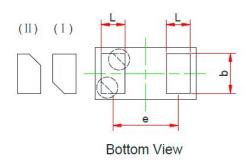
Device	Package	Qty per Reel	Reel Size
SSCE3V382N1	DFN1006-2L	10000	7 Inch

Mechanical Data

Case:DFN1006-2L

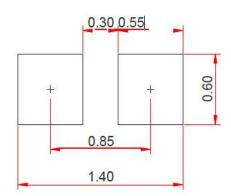
Case Material: Molded Plastic. UL Flammability





DIM	Millimeters			
DIIVI	Min	Тур	Max	
Α	0.340	0.450	0.530	
A1	0.000	0.020	0.050	
А3	0.125REF			
D	0.950	1.000	1.080	
E	0.550	0.600	0.680	
b	0.450	0.500	0.550	
L	0.200	0.250	0.300	
е	0.650BSC			

Recommended Pad outline (Unit: mm)





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